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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# DB3S308F

## Silicon epitaxial planar type

For high speed switching circuits

### ■ Features

- Short reverse recovery time  $t_{rr}$
- Low forward voltage  $V_F$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

### ■ Marking Symbol: 4T

### ■ Basic Part Number

Dual DB2S308 (Series)

### ■ Packaging

DB3S308F0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average)	Single	100	mA
	Series	75	
Peak forward current	Single	200	mA
	Series	150	
Non-repetitive peak forward surge current *1	$I_{FSM}$	1	A
Junction temperature	$T_j$	125	$^\circ\text{C}$
Operating ambient temperature	$T_{opr}$	-40 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

Note) \*1: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

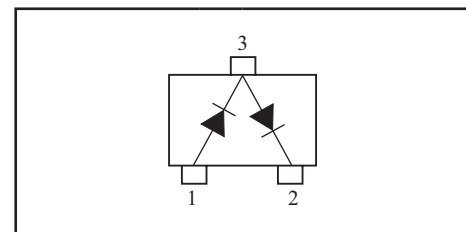
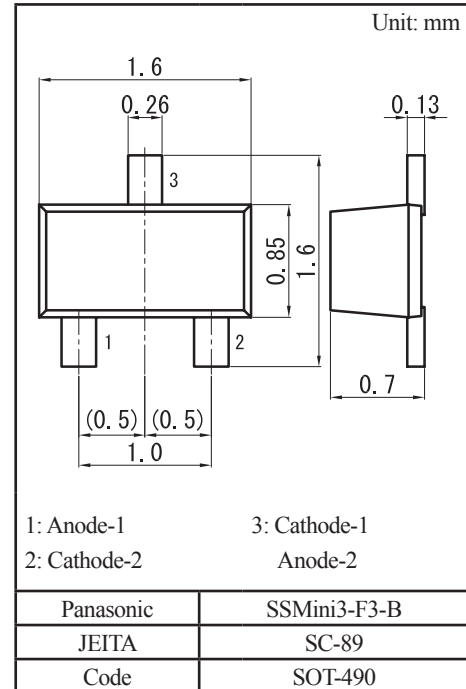
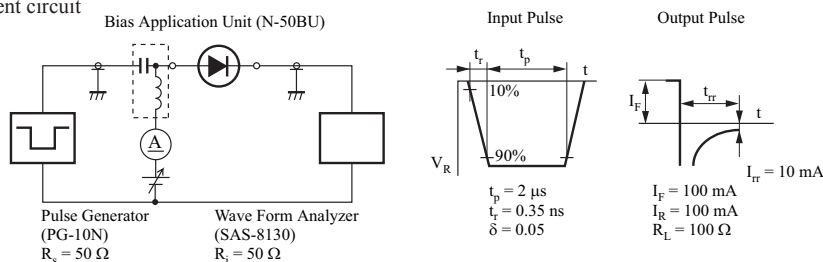
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 10 \text{ mA}$			0.29	V
	$V_{F2}$	$I_F = 100 \text{ mA}$			0.42	
Reverse current	$I_{R1}$	$V_R = 10 \text{ V}$			25	$\mu\text{A}$
	$I_{R2}$	$V_R = 30 \text{ V}$			120	
Terminal capacitance	$C_t$	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		2.9		pF
Reverse recovery time *1	$t_{rr}$	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		1.3		ns

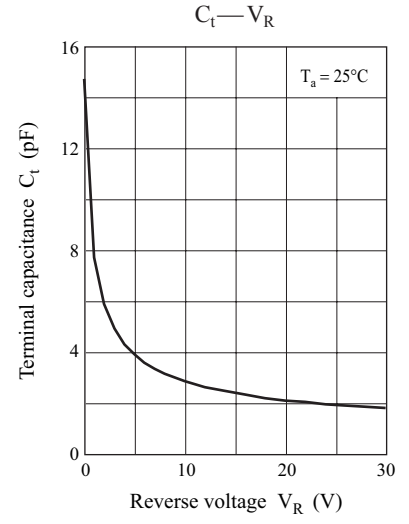
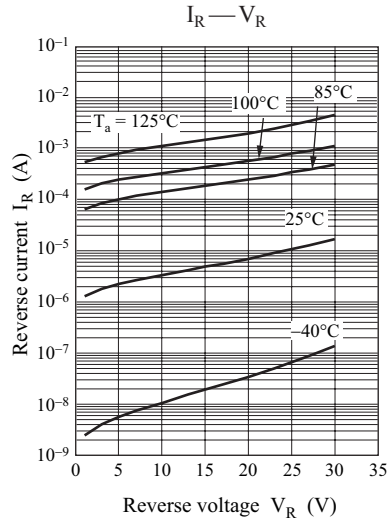
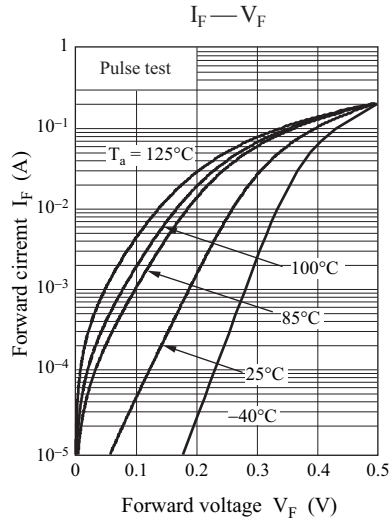
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz

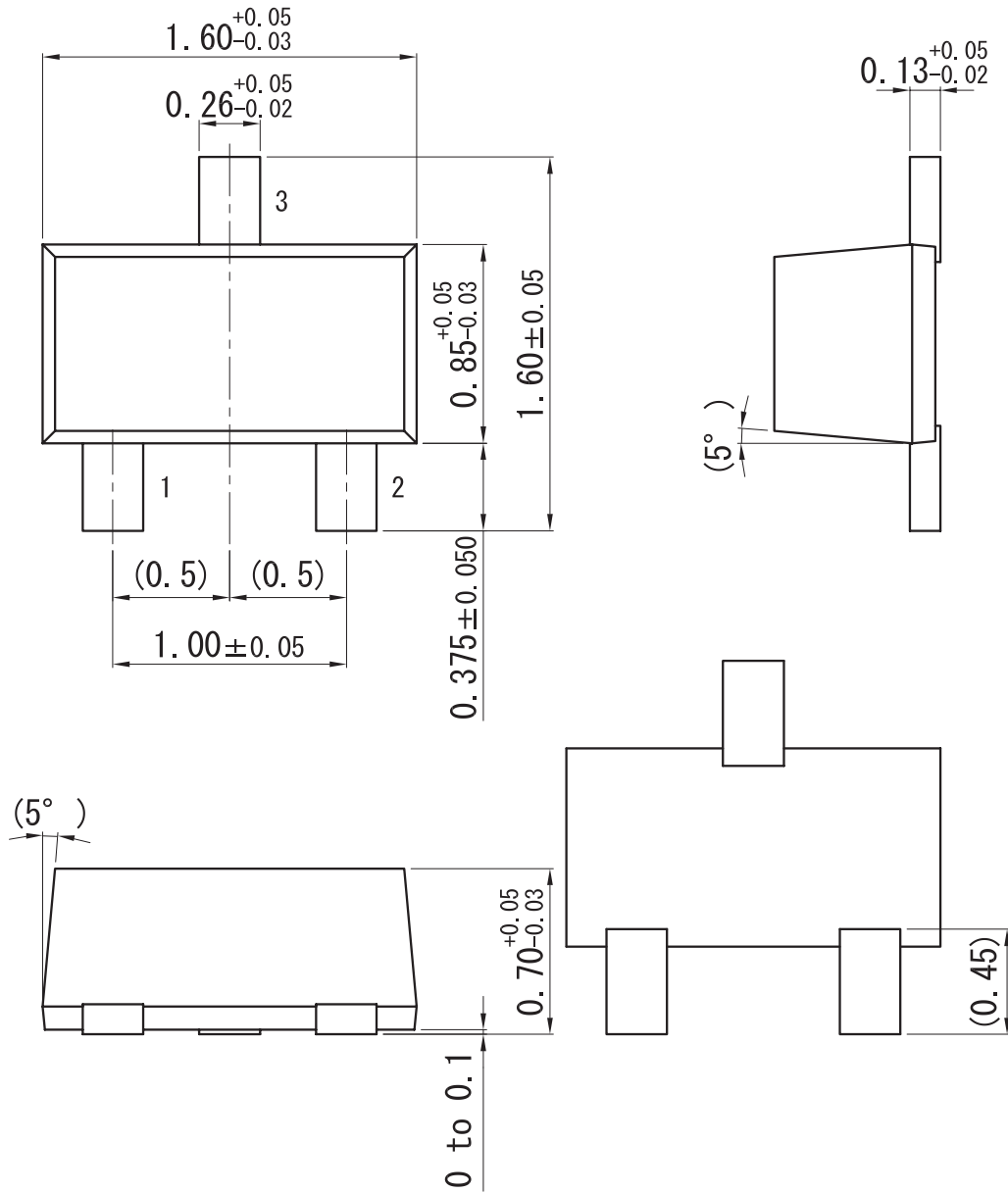
\*1:  $t_{rr}$  measurement circuit



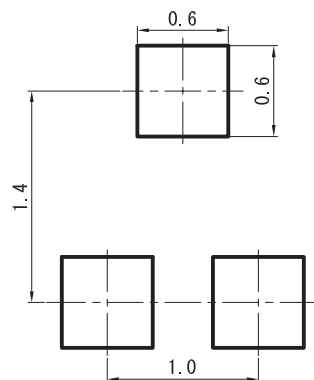


SSMini3-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)





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